

**CoolMOS® Power Transistor**
**Features**

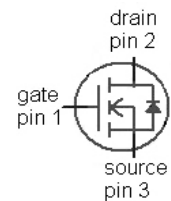
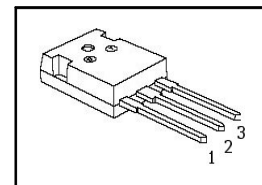
- Worldwide best  $R_{ds,on}$  in TO247
- Ultra low gate charge
- Extreme dv/dt rated
- High peak current capability
- Qualified for industrial grade applications according to JEDEC<sup>1)</sup>
- Pb-free lead plating; RoHS compliant

**Product Summary**

|                     |       |          |
|---------------------|-------|----------|
| $V_{DS} @ T_{jmax}$ | 650   | V        |
| $R_{DS(on),max}$    | 0.045 | $\Omega$ |
| $Q_{g,typ}$         | 150   | nC       |

**CoolMOS CP is specially designed for:**

- Hard switching SMPS topologies

**PG-TO247-3-1**


| Type        | Package      | Ordering Code | Marking |
|-------------|--------------|---------------|---------|
| IPW60R045CP | PG-TO247-3-1 | SP000067149   | 6R045   |

**Maximum ratings, at  $T_j=25\text{ °C}$ , unless otherwise specified**

| Parameter   | Symbol         | Conditions                            | Value       | Unit               |
|---|----------------|---------------------------------------|-------------|--------------------|
| Continuous drain current                                | $I_D$          | $T_C=25\text{ °C}$                    | 60          | A                  |
|   |                | $T_C=100\text{ °C}$                   | 38          |                    |
| Pulsed drain current <sup>2)</sup>                      | $I_{D,pulse}$  | $T_C=25\text{ °C}$                    | 230         |                    |
| Avalanche energy, single pulse                          | $E_{AS}$       | $I_D=11\text{ A}, V_{DD}=50\text{ V}$ | 1950        | mJ                 |
| Avalanche energy, repetitive $t_{AR}$ <sup>2),3)</sup>  | $E_{AR}$       | $I_D=11\text{ A}, V_{DD}=50\text{ V}$ | 3           |                    |
| Avalanche current, repetitive $t_{AR}$ <sup>2),3)</sup> | $I_{AR}$       |                                       | 11          | A                  |
| MOSFET dv/dt ruggedness                                 | dv/dt          | $V_{DS}=0\dots 480\text{ V}$          | 50          | V/ns               |
| Gate source voltage                                     | $V_{GS}$       | static                                | $\pm 20$    | V                  |
|   |                | AC ( $f > 1\text{ Hz}$ )              | $\pm 30$    |                    |
| Power dissipation                                       | $P_{tot}$      | $T_C=25\text{ °C}$                    | 431         | W                  |
| Operating and storage temperature                       | $T_j, T_{stg}$ |                                       | -55 ... 150 | $^{\circ}\text{C}$ |
| Mounting torque   |                | M3 and M3.5 screws                    | 60          | Ncm                |

**Maximum ratings**, at  $T_j=25\text{ °C}$ , unless otherwise specified

| Parameter                           | Symbol        | Conditions         | Value | Unit |
|-------------------------------------|---------------|--------------------|-------|------|
| Continuous diode forward current    | $I_S$         | $T_C=25\text{ °C}$ | 44    | A    |
| Diode pulse current <sup>2)</sup>   | $I_{S,pulse}$ |                    | 230   |      |
| Reverse diode $dv/dt$ <sup>4)</sup> | $dv/dt$       |                    | 15    | V/ns |

| Parameter | Symbol | Conditions | Values |      |      | Unit |
|-----------|--------|------------|--------|------|------|------|
|           |        |            | min.   | typ. | max. |      |

**Thermal characteristics**

|  |            |                                       |   |   |      |     |
|--|------------|---------------------------------------|---|---|------|-----|
| Thermal resistance, junction - case                        | $R_{thJC}$ |                                       | - | - | 0.29 | K/W |
| Thermal resistance, junction - ambient                     | $R_{thJA}$ | leaded                                | - | - | 62   |     |
| Soldering temperature, wavesoldering only allowed at leads | $T_{sold}$ | 1.6 mm (0.063 in.) from case for 10 s | - | - | 260  | °C  |

**Electrical characteristics**, at  $T_j=25\text{ °C}$ , unless otherwise specified

**Static characteristics**

|                                  |               |   |     |      |       |               |
|----------------------------------|---------------|---|-----|------|-------|---------------|
| Drain-source breakdown voltage   | $V_{(BR)DSS}$ | $V_{GS}=0\text{ V}$ , $I_D=250\text{ }\mu\text{A}$                | 600 | -    | -     | V             |
| Gate threshold voltage           | $V_{GS(th)}$  | $V_{DS}=V_{GS}$ , $I_D=3\text{ mA}$                               | 2.5 | 3    | 3.5   |               |
| Zero gate voltage drain current  | $I_{DSS}$     | $V_{DS}=600\text{ V}$ , $V_{GS}=0\text{ V}$ , $T_j=25\text{ °C}$  | -   | -    | 10    | $\mu\text{A}$ |
|                                  |               | $V_{DS}=600\text{ V}$ , $V_{GS}=0\text{ V}$ , $T_j=150\text{ °C}$ | -   | 50   | -     |               |
| Gate-source leakage current      | $I_{GSS}$     | $V_{GS}=20\text{ V}$ , $V_{DS}=0\text{ V}$                        | -   | -    | 100   | nA            |
| Drain-source on-state resistance | $R_{DS(on)}$  | $V_{GS}=10\text{ V}$ , $I_D=44\text{ A}$ , $T_j=25\text{ °C}$     | -   | 0.04 | 0.045 | $\Omega$      |
|                                  |               | $V_{GS}=10\text{ V}$ , $I_D=44\text{ A}$ , $T_j=150\text{ °C}$    | -   | 0.11 | -     |               |
| Gate resistance                  | $R_G$         | $f=1\text{ MHz}$ , open drain                                     | -   | 1.3  | -     | $\Omega$      |

| Parameter | Symbol | Conditions | Values |      |      | Unit |
|-----------|--------|------------|--------|------|------|------|
|           |        |            | min.   | typ. | max. |      |

**Dynamic characteristics**

|  |              |   |   |      |   |    |
|--|--------------|---|---|------|---|----|
| Input capacitance  | $C_{iss}$    | $V_{GS}=0\text{ V}, V_{DS}=100\text{ V},$<br>$f=1\text{ MHz}$                         | - | 6800 | - | pF |
| Output capacitance   | $C_{oss}$    |   | - | 320  | - |    |
| Effective output capacitance, energy related <sup>5)</sup> | $C_{o(er)}$  | $V_{GS}=0\text{ V}, V_{DS}=0\text{ V}$<br>to 480 V                                    | - | 310  | - |    |
| Effective output capacitance, time related <sup>6)</sup>   | $C_{o(tr)}$  |   | - | 820  | - |    |
| Turn-on delay time   | $t_{d(on)}$  | $V_{DD}=400\text{ V},$<br>$V_{GS}=10\text{ V}, I_D=44\text{ A},$<br>$R_G=3.3\ \Omega$ | - | 30   | - | ns |
| Rise time  | $t_r$        |   | - | 20   | - |    |
| Turn-off delay time  | $t_{d(off)}$ |   | - | 100  | - |    |
| Fall time  | $t_f$        |   | - | 10   | - |    |

**Gate Charge Characteristics**

|                       |               |   |   |     |     |    |
|-----------------------|---------------|---|---|-----|-----|----|
| Gate to source charge | $Q_{gs}$      | $V_{DD}=400\text{ V}, I_D=44\text{ A},$<br>$V_{GS}=0\text{ to }10\text{ V}$ | - | 34  | -   | nC |
| Gate to drain charge  | $Q_{gd}$      |   | - | 51  | -   |    |
| Gate charge total     | $Q_g$         |   | - | 150 | 190 |    |
| Gate plateau voltage  | $V_{plateau}$ |   | - | 5.0 | -   | V  |

**Reverse Diode**

|                               |           |   |   |     |     |               |
|-------------------------------|-----------|---|---|-----|-----|---------------|
| Diode forward voltage         | $V_{SD}$  | $V_{GS}=0\text{ V}, I_F=44\text{ A},$<br>$T_j=25\text{ }^\circ\text{C}$ | - | 0.9 | 1.2 | V             |
| Reverse recovery time         | $t_{rr}$  | $V_R=400\text{ V}, I_F=I_S,$<br>$di_F/dt=100\text{ A}/\mu\text{s}$      | - | 600 | -   | ns            |
| Reverse recovery charge       | $Q_{rr}$  |   | - | 17  | -   | $\mu\text{C}$ |
| Peak reverse recovery current | $I_{rrm}$ |   | - | 60  | -   | A             |

<sup>1)</sup> J-STD20 and JESD22

<sup>2)</sup> Pulse width  $t_p$  limited by  $T_{j,max}$

<sup>3)</sup> Repetitive avalanche causes additional power losses that can be calculated as  $P_{AV}=E_{AR} \cdot f$ .

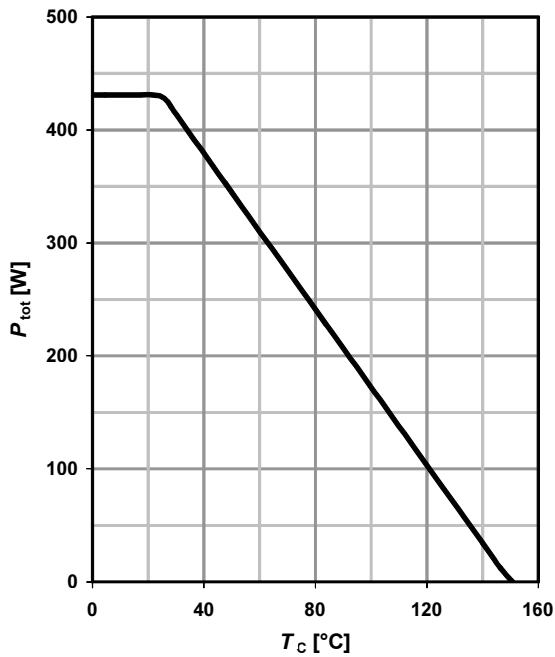
<sup>4)</sup>  $I_{SD} \leq I_D, di/dt \leq 100\text{ A}/\mu\text{s}, V_{DClink} = 400\text{ V}, V_{peak} < V_{(BR)DSS}, T_j < T_{j,max}$ , identical low side and high side switch

<sup>5)</sup>  $C_{o(er)}$  is a fixed capacitance that gives the same stored energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 80%  $V_{DSS}$ .

<sup>6)</sup>  $C_{o(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 80%  $V_{DSS}$ .

**1 Power dissipation**

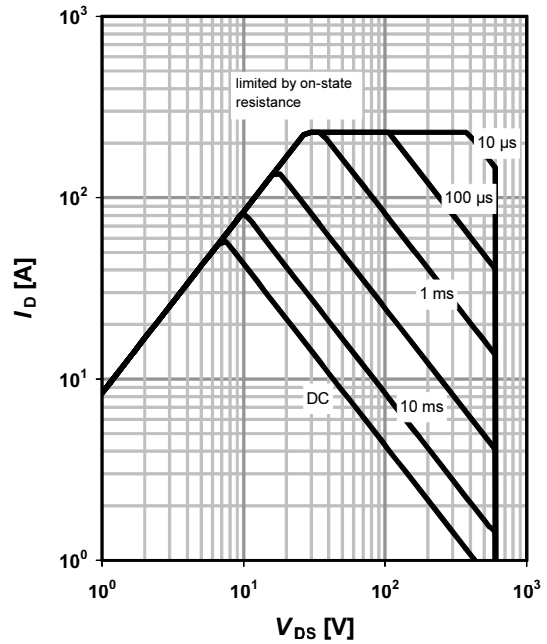
$P_{tot}=f(T_C)$



**2 Safe operating area**

$I_D=f(V_{DS}); T_C=25\text{ °C}; D=0$

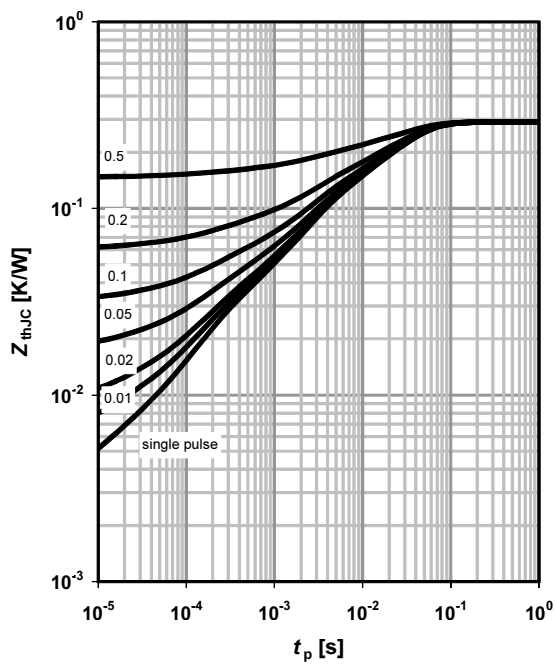
parameter:  $t_p$



**3 Max. transient thermal impedance**

$Z_{(th)C}=f(t_p)$

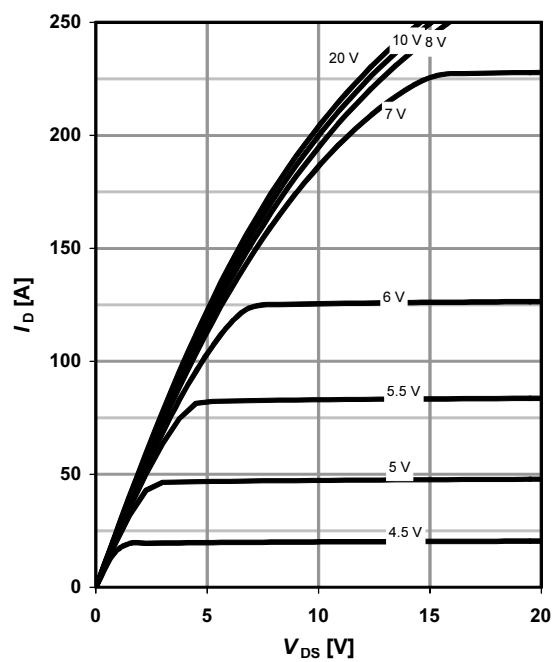
parameter:  $D=t_p/T$



**4 Typ. output characteristics**

$I_D=f(V_{DS}); T_J=25\text{ °C}$

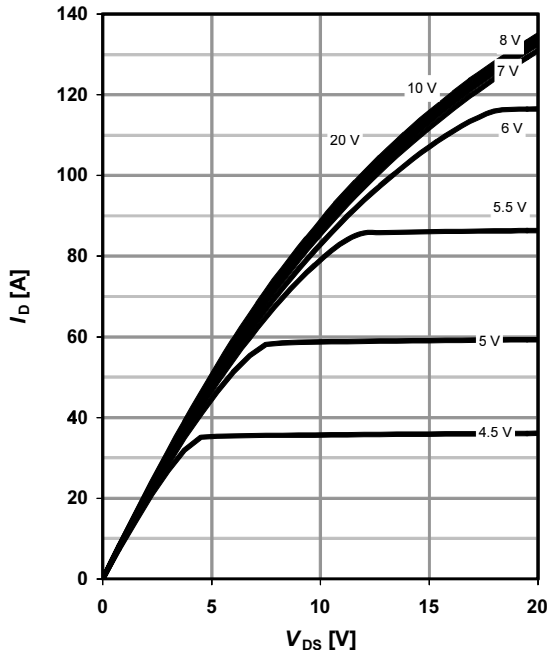
parameter:  $V_{GS}$



**5 Typ. output characteristics**

$I_D = f(V_{DS}); T_j = 150\text{ °C}$

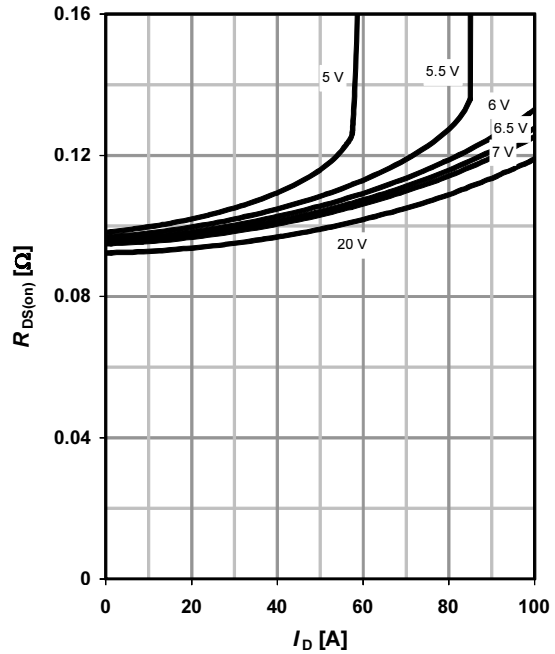
parameter:  $V_{GS}$



**6 Typ. drain-source on-state resistance**

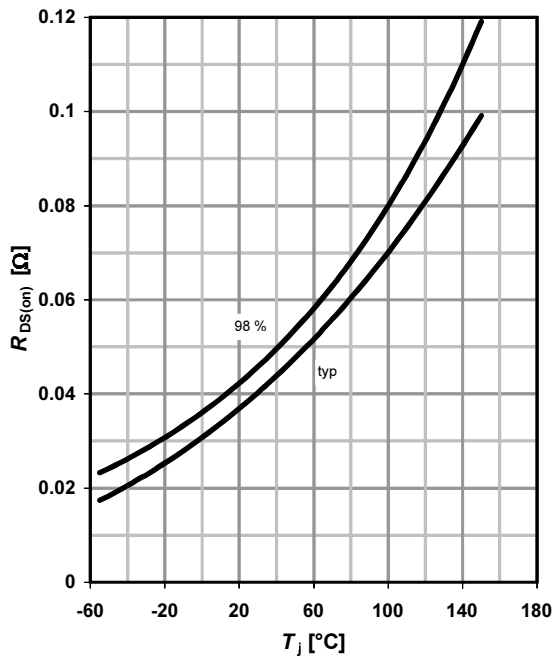
$R_{DS(on)} = f(I_D); T_j = 150\text{ °C}$

parameter:  $V_{GS}$



**7 Drain-source on-state resistance**

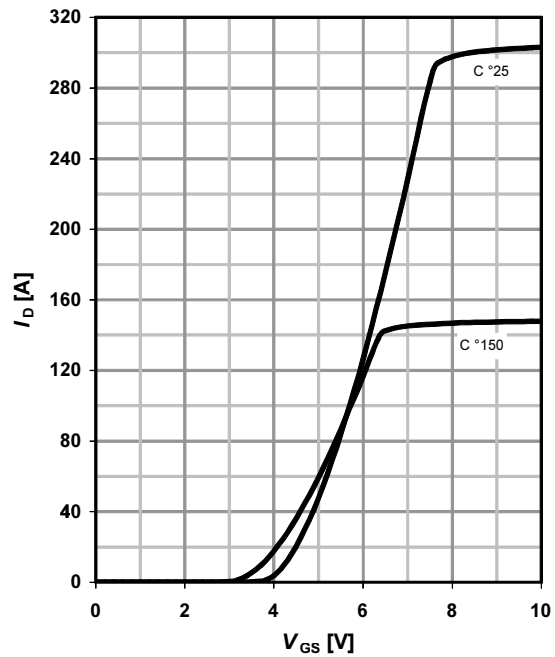
$R_{DS(on)} = f(T_j); I_D = 44\text{ A}; V_{GS} = 10\text{ V}$



**8 Typ. transfer characteristics**

$I_D = f(V_{GS}); |V_{DS}| > 2|I_D|R_{DS(on)max}$

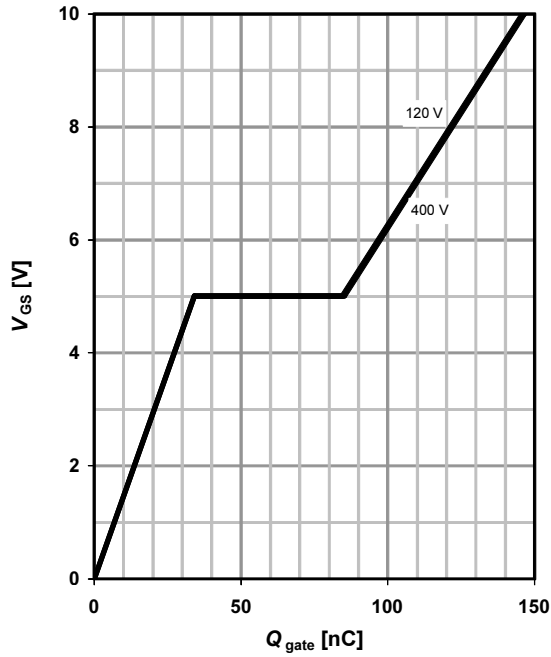
parameter:  $T_j$



**9 Typ. gate charge**

$V_{GS}=f(Q_{gate}); I_D=44\text{ A pulsed}$

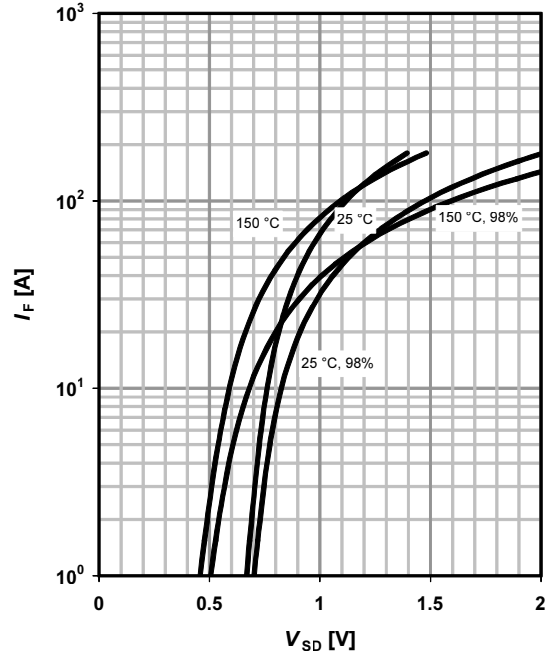
parameter:  $V_{DD}$



**10 Forward characteristics of reverse diode**

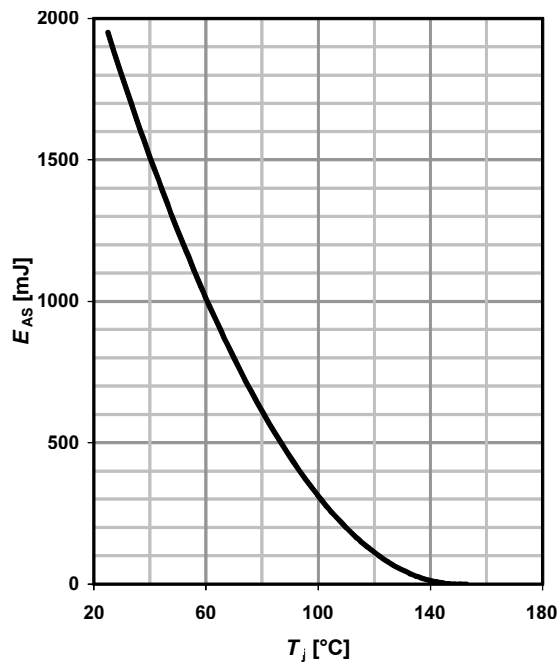
$I_F=f(V_{SD})$

parameter:  $T_j$



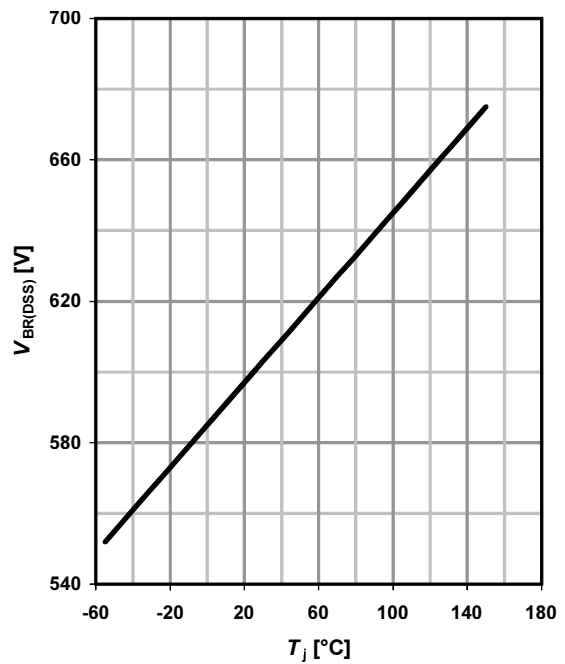
**11 Avalanche energy**

$E_{AS}=f(T_j); I_D=11\text{ A}; V_{DD}=50\text{ V}$



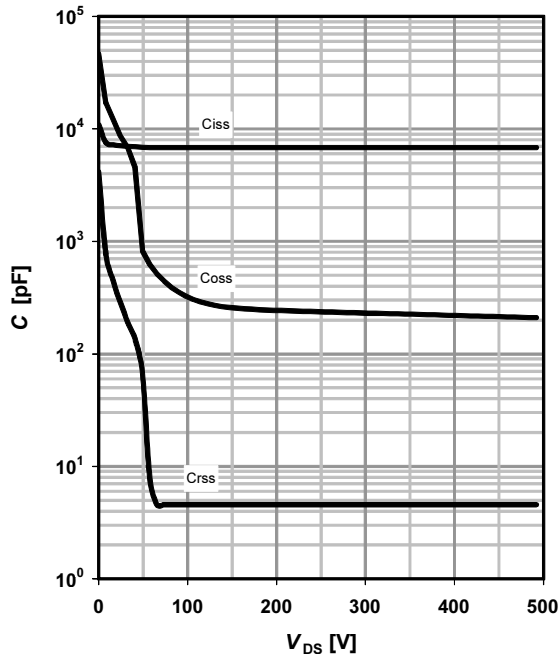
**12 Drain-source breakdown voltage**

$V_{BR(DSS)}=f(T_j); I_D=0.25\text{ mA}$



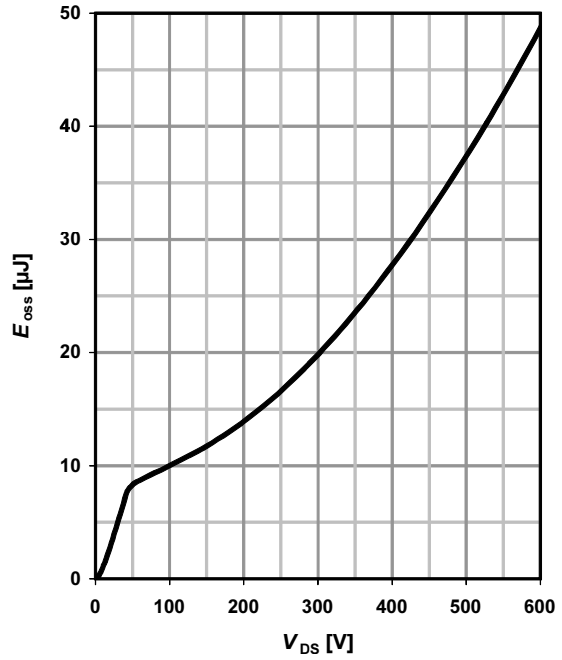
13 Typ. capacitances

$C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$



14 Typ. Coss stored energy

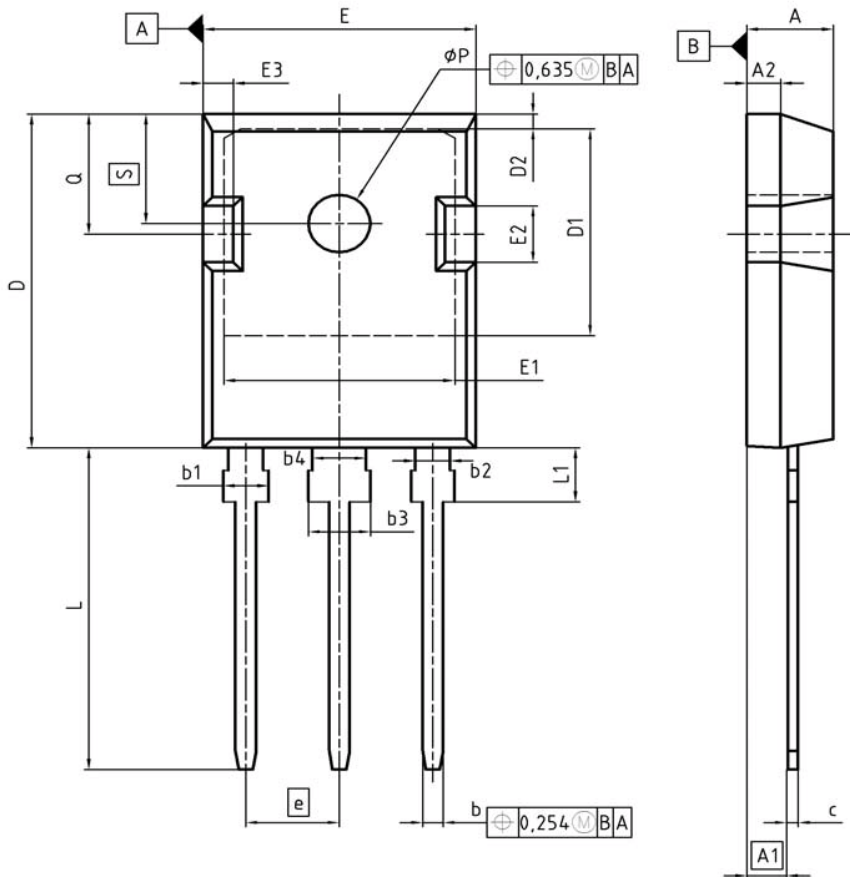
$E_{oss} = f(V_{DS})$



Definition of diode switching characteristics







| DIM | MILLIMETERS |       | INCHES |       |
|-----|-------------|-------|--------|-------|
|     | MIN         | MAX   | MIN    | MAX   |
| A   | 4.90        | 5.16  | 0.193  | 0.203 |
| A1  | 2.27        | 2.53  | 0.089  | 0.099 |
| A2  | 1.85        | 2.11  | 0.073  | 0.083 |
| b   | 1.07        | 1.33  | 0.042  | 0.052 |
| b1  | 1.90        | 2.41  | 0.075  | 0.095 |
| b2  | 1.90        | 2.16  | 0.075  | 0.085 |
| b3  | 2.87        | 3.38  | 0.113  | 0.133 |
| b4  | 2.87        | 3.13  | 0.113  | 0.123 |
| c   | 0.55        | 0.68  | 0.022  | 0.027 |
| D   | 20.82       | 21.10 | 0.820  | 0.831 |
| D1  | 16.25       | 17.65 | 0.640  | 0.695 |
| D2  | 1.05        | 1.35  | 0.041  | 0.053 |
| E   | 15.70       | 16.03 | 0.618  | 0.631 |
| E1  | 13.10       | 14.15 | 0.516  | 0.557 |
| E2  | 3.68        | 5.10  | 0.145  | 0.201 |
| E3  | 1.68        | 2.60  | 0.066  | 0.102 |
| e   | 5.44        |       | 0.214  |       |
| N   | 3           |       | 3      |       |
| L   | 19.80       | 20.31 | 0.780  | 0.799 |
| L1  | 4.17        | 4.47  | 0.164  | 0.176 |
| φP  | 3.50        | 3.70  | 0.138  | 0.146 |
| Q   | 5.49        | 6.00  | 0.216  | 0.236 |
| S   | 6.04        | 6.30  | 0.238  | 0.248 |

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# 1 New package outlines TO-247

Assembly capacity extension for CoolMOSTM technology products assembled in lead-free package PG-TO247-3 at subcontractor ASE (Weihai) Inc., China (Changes are marked in blue.)



Figure 1 Outlines TO-247, dimensions in mm/inches